

RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

DESCRIPTION

These miniature surface mount MOSFETs reduce power loss conserve energy, making this device ideal for use in small power management circuitry.

FEATURES

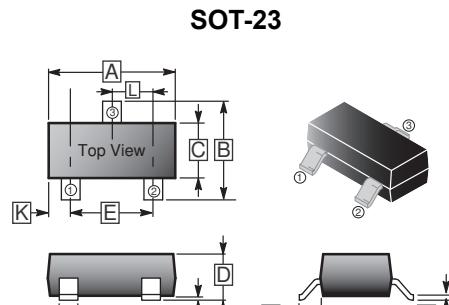
- Energy Efficient
- Low Threshold Voltage
- High-speed Switching
- Miniature Surface Mount Package Saves Board Space

MARKING

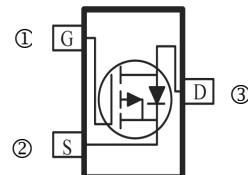
B84

PACKAGE INFORMATION

| Package | MPQ | Leader Size |
|---------|-----|-------------|
| SOT-23 | 3K | 7 inch |



| REF. | Millimeter | | REF. | Millimeter | |
|------|------------|------|------|------------|-------|
| | Min. | Max. | | Min. | Max. |
| A | 2.80 | 3.04 | G | 0.09 | 0.18 |
| B | 2.10 | 2.55 | H | 0.45 | 0.60 |
| C | 1.20 | 1.40 | J | 0.08 | 0.177 |
| D | 0.89 | 1.15 | K | 0.6 | REF. |
| E | 1.78 | 2.04 | L | 0.89 | 1.02 |
| F | 0.30 | 0.50 | | | |



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Rating | Unit |
|---|-----------------|--------------|--------|
| Drain-Source Voltage | V_{DS} | -50 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Continuous Drain Current | I_D | -0.13 | A |
| Pulsed Drain Current ¹ | I_{DM} | -0.52 | A |
| Power Dissipation | P_D | 225 | mW |
| Lead Temperature for Soldering Purposes(1/8" from case for 5 s) | T_L | 260 | °C |
| Operating Junction & Storage Temperature | T_J, T_{STG} | 150, -55~150 | °C |
| Thermal Resistance Ratings | | | |
| Thermal Resistance Junction-ambient ² | $R_{\theta JA}$ | 556 | °C / W |

ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise specified)

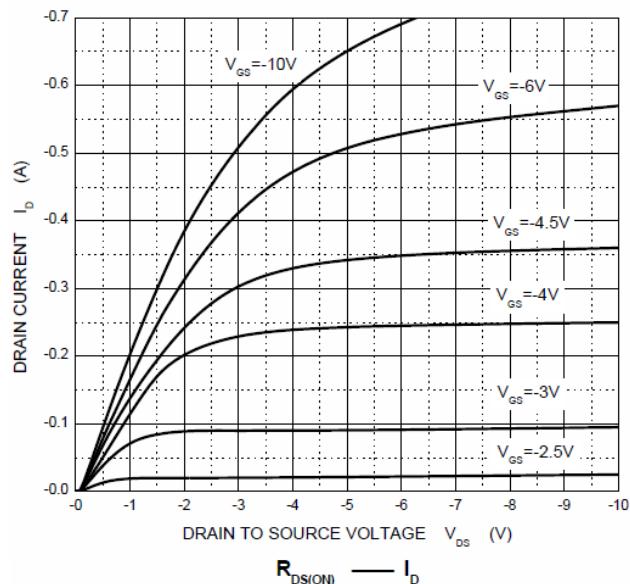
| Parameter | Symbol | Min. | Typ. | Max. | Unit | Test Conditions |
|--|---------------------|------|------|---------|---------------|--|
| Drain-Source Breakdown Voltage | $V_{(BR)DSS}$ | -50 | - | - | V | $V_{GS}=0$, $I_D=-250\mu\text{A}$ |
| Drain-Source Leakage Current | I_{GSS} | - | - | ± 5 | μA | $V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$ |
| Gate-Source Leakage Current | I_{DSS} | - | - | -15 | μA | $V_{GS}=0\text{V}$, $V_{DS}=-50\text{V}$ |
| | | - | - | -0.1 | | $V_{GS}=0\text{V}$, $V_{DS}=-25\text{V}$ |
| Gate-Threshold Voltage ³ | $V_{GS(\text{th})}$ | -0.9 | -1.6 | -2 | V | $V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$ |
| Forward Transconductance ¹ | g_{fs} | 50 | - | - | mS | $V_{DS}=-25\text{V}$, $I_D=-100\text{mA}$ |
| Static Drain-Source On-Resistance ³ | $R_{DS(\text{ON})}$ | - | 5.8 | 10 | Ω | $V_{GS}=-5\text{V}$, $I_D=-0.1\text{A}$ |
| | | - | 4.5 | 8 | | $V_{GS}=-10\text{V}$, $I_D=0.1\text{A}$ |
| Input Capacitance | C_{iss} | - | 30 | - | pF | $V_{GS}=0\text{V}$ |
| Output Capacitance | C_{oss} | - | 10 | - | | $V_{DS}=-5\text{V}$ |
| Reverse Transfer Capacitance | C_{rss} | - | 5 | - | | $f=1\text{MHz}$ |
| Turn-on Delay Time | $T_{d(\text{on})}$ | - | 2.5 | - | nS | $V_{DD}=-15\text{V}$ $R_L=50\Omega$, $I_D=-2.5\text{A}$ |
| Rise Time | T_r | - | 1 | - | | |
| Turn-off Delay Time | $T_{d(\text{off})}$ | - | 16 | - | | |
| Fall Time | T_f | - | 8 | - | | |
| Source-Drain Diode | | | | | | |
| Continuous Current | I_s | - | - | -0.13 | A | |
| Pulsed Current | I_{SM} | - | - | -0.52 | A | |
| Diode Forward Voltage ³ | V_{SD} | - | - | -2.2 | V | $I_s=-0.13\text{A}$, $V_{GS}=0\text{V}$ |

Notes:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board $t \leq 10\text{s}$.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.

CHARACTERISTIC CURVES

Output Characteristics



Transfer Characteristics

